

Industrial SCSI Connector

1. Scope

1.1 Contents

This specification covers the requirements for product performance, test methods and quality assurance provisions of SCSI Connector.

2. Applicable Documents:

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence.

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2.1 TE Specifications:

A. 501-106126: Qualification Test Report

2.2 Commercial Standards and Specifications:

A. EIA364 series

3. Requirements:

3.1 Design and Construction:

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2 Materials:

A. Contact:

Material: Copper alloy

Finish: Nickel plating all over Contact area: Au plating Soldering area: Tin plating

B. Housing:

Material: High Temperature Thermo plastic, Glass Filled

Flammability: UL94 V-0

C. Shell:



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Material: Steel Finish: Nickel plating

3.3 Ratings:

A. Voltage Rating: 200V AC (rms)

B. Current Rating: 1A

C. Temperature Rating: -40℃ to +85℃

3.4 Performance Requirements and Test Descriptions :

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Fig.1.

3.4.1 Test Environment

All tests shall be performed in the environmental conditions listed below,

Unless otherwise specified.

Temperature: 15° C to 35° C Humidity: 20° to 80° RH Atmospheric Pressure: 650 to 800° m Hg



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3.5 Test Requirements and Procedures Summary

Para Test Items		Requirements	Procedures				
3.5.1	Examination of	Meets requirements of	Visual inspection No physical damage.				
	Product	product drawing.					
		Electrical Require	ments				
3.5.2	Contact Resistance	40 mΩMax. (Initial)	Subject a voltage of 20mV Max open circuit at				
	(Low Level)	55 mΩMax. (After Test)	100mA on mated contacts assemblies per EIA364-23				
3.5.3	Insulation	500MΩMin.	500V DC for 1minute between adjacent circuits				
	Resistance		of mated connectors.				
			EIA364-21				
3.5.4	Dielectric	No creeping discharge or	500V AC for 1minute between adjacent circuits				
	withstanding Voltage	flashover shall occur.	of mated connectors.				
		Leak current: 0.5mA Max.	EIA364-20 Method B				
3.5.5	Temperature Rising	Temperature rise shall not	Wire contact P1, P2, P8 & P9 in parallel for				
	(apply only to 15	exceed 30℃ after 20 hours	power. Wire contact P4, P5, P6 P10 & P12 in				
	positions)	(45 minutes ON and 15	parallel for return.				
		minutes OFF per hour).	Apply 6A total DC current to parallel contacts				
		Ambition condition is 25℃	P1, P2, P8 & P9 and return from parallel				
		at still air.	contacts P4, P5, P6 P10 & P12				
		Mechanical Require	ements				
3.5.6	Connector	0.15KG per contact Max.	Operation speed: 25mm/min.				
	Mating Force		Measure force necessary to mate samples.				
			EIA364-13				
3.5.7	Connector	0.04KG per contact Min.	Operation speed: 25mm/min.				
	Un-mating Force		Measure force necessary to un-mate samples				
	J		EIA364-13				
3.5.8	Durability	See note.	Operation Speed :40cycles/hour				
0.0.0	(Repeated	Oct Hote.	No. of Cycles: 500cycles.				
	Mate/Un-mating)		EIA364-09				
3.5.9	Vibration	No electrical discontinuity	Subject mated connectors to 10-55-10 Hz				
	(Random)	greater than 1µsec shall	traversed in 1 minute at 1.52mm amplitude 2				
	(Tallaoili)	occur.	hours each of 3 mutually perpendicular planes				
		000011	basis of o matadily perpendicular planes				

Fig.1 (CONT.)

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48 hours EIA364-26

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NOTE

Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Re qualification Test Sequence shown in Figure 2.

Fig. 1 (END)

3.5 Product Qualification Test Sequence

	Test Group								
Test Examination	1	2	3	4	5	6	7	8	
	Test Sequence(a)								
Examination of Product	1,5	1,9	1,8	1,8	1,7	1,5	1,3	1	
Low level Contact Resistance	2,4	3,7	2,4,6		4,6	2,4		2,4	
Insulation Resistance				2,6					
Dielectric withstanding Voltage				3,7					
Temperature Rising			7						
Conn. Mating Force		2							
Conn. Un-mating Force		8							
Durability	3	4(b)			2(b)				
Vibration		5							
Physical Shock		6							
Reseating (manually									
plug/unplug 3 time)			5		5				
Solder ability							2		
Resistance to Solder Heat						3			
Temperature Life(Heat Aging)			3						
Humidity (Steady State)				5					
Thermal Shock				4					
Mixed Flowing Gas					3			_	
Salt Spray								3	

FIG 2

- (a) Numbers indicate sequence in which tests are performed.
- (b) Preconditioning, 20 cycles for the 50-durability cycle requirement, 50 cycles for the 500-durability cycle requirement. The mating and un-mating cycle is at the maximum rate of 200 cycles per hour.





4. QUALITY ASSURANCE PEOVISIONS

4.1 Qualification Testing

A. Specimen Selection

Plugs and jacks shall be prepared in accordance with applicable Instruction Sheet and shall be selected at random from current production. Each test group shall consist of a minimum of 5 specimens unless otherwise stated.

В. **Test Sequence**

Qualification inspection shall be verified by testing specimens as specified in figure 3.

4.2 Requalification testing

If changes significantly affecting form, fit or function are made to the product or manufacturing process or controlling industry specification, product assurance, shall coordinate requalification testing, consisting of all or part of the original testing sequence as determined by development/product, quality and reliability engineers.

4.3 Acceptance

Acceptance is based on verification that the product meets the requirements of Figure 2. Failures attributed to equipment, test setup or operator deficiencies shall not disqualify the product. If product failure occurs, corrective action shall be taken and samples resubmitted for qualification. Testing to confirm corrective action is required before resubmitted.

4.4 Quality conformance Inspection

The applicable quality inspection plan shall specify the sampling acceptable quality level to be used. Dimensional and functional requirements shall be in accordance with the applicable product drawing and this specification.